SN54276, SN74276 QUADRUPLE J·K FLIP-FLOPS

- Four J-K Flip-Flops in a Single Package . . . Can Reduce FF Package Count by 50%
- Separate Negative-Edge-Triggered Clocks with Hysteresis . . . Typically 200 mV
- Typical Clock Input Frequency . . . 50 MHz
- Fully Buffered Outputs

description

These quadruple TTL J- \overline{K} flip-flops incorporate a number of third-generation IC features that can simplify system design and reduce flip-flop package count by up to 50%. They feature hysteresis at each clock input, fully buffered outputs, and direct clear capability, and are presettable through a buffer that also features an input hysteresis loop. The negative-edge-triggering clocks are directly compatible with earlier Series 54/74 single and dual pulse-triggered flip-flops. These circuits can be used to emulate D- or T-type flip-flops by hard-wiring the inputs, or to implement asychronous sequential functions.

The SN54276 is characterized for operation over the full military temperature range of -55° C to 125° C; the SN74726 is characterized for operation from 0°C to 70°C.

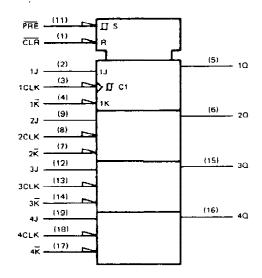
FUNCTION	TABLE	{EACH	FLIP-FLOP)
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COMMON	COMMON INPUTS		INPUTS		
PRE	CLR	CLK	ſ	ĸ	a
L	н	x	х	х	н
н	L	x	х	x	L
L	L	x	х	х	н [†]
н	н	4	L	н	0 ₀
н	н	4	н	н	н
н	н	I	L	L	L
н	н	1	н	L	TOGGLE
Н	н	н	×	×	QÜ

[†] This configuration is nonstable; that is, it may not oersist when preset and clear return to their inactive (high) level. OCTOBER 1976 - REVISED MARCH 1988

SN54276 J PACKAGE SN74276 N PACKAGE (TOP VIEW)							
CLR 1J 1CLK 1K 2Q 2K 2CLK GND	1 2 3 4 5 6 7 8 9 10	20 19 18 17 16 15 14 13 12 11	VCC 4J 4CLK 4K 4Q 3Q 3K 3CLK 3J PRE				

logic symbol[‡]

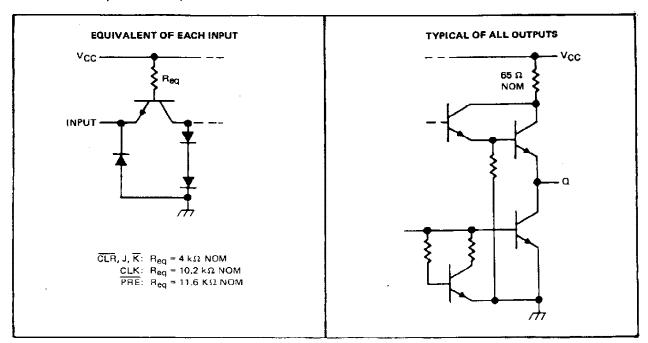


[‡]This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

PRODUCTION DATA documents centain information current as of publication date. Products conform to specifications per the terms of Texes instruments standard warranty. Production processing daes not necessarily include testing of all parameters.



OST OFFICE BOX 655012 + DALLAS TEXAS 7526



schematics of inputs and outputs

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

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Operating free-air temperature range:	SN54276	55°C to 125°C
Storage temperature range		– 65°C to 150°C
NOTE 1: Voltage values are with respect to netw	ork ground terminal.	



SN54276, SN74276 QUADRUPLE J-K FLIP-FLOPS

recommended operating conditions

		SN54276		SN74276					
	_	MIN	NOM	MAX	MIN	NOM	MAX		
Supply voltage, VCC		4.5	5	5.5	4,75	5	5.25	V	
High-level output cur	rent, IOH			800			-800	μA	
Low-level output curi	rent, IQL			16	1		16	mA	
Clock frequency		0		35	0		35	MH	
	Clock high	13.5			13,5				
Pulse width, tw	Clock low	15			15			ាន	
	Preset or clear low	12			12				
	J, K inputs	31			34			ns	
Setup time, t _{su}	Clear and preset inactive state	10↓			104				
Input hold time, th		101			104			ns	
Operating free-air temperature, TA		-55		125	0		70	°C	

1 The arrow indicates that the falling edge of the clock pulse is used for reference.

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST CO	NDITIONST	MIN	түр‡	MAX	UNIT
⊻н	High-level input voltage			2			V
VIL	Low-level input voltage					0.8	V
VIK	Input clamp voltage	V _{CC} = MIN,	1 ₁ = -12 mA			-1.5	V
∨он	High-level output voltage	V _{CC} = MIN, V _{IL} = 0.8 V,	V _{IH} ≈ 2 V, I _{OH} ≈ -800 µA	2.4	3.4		v
V _{OL}	Low-level output voltage	V _{CC} = MIN, V _{1L} = 0.8 V,	V _{IH} = 2 V, IOL = 16 mA		0.2	0,4	v
4	Input current at maximum input voltage	V _{CC} = MAX,	V ₁ = 5.5 V			1	mА
<u>.</u> Чн	High-level input current	VCC = MAX,	V1 = 2.4 V			40	μA
ŧ۱L	Low-level input current	VCC - MAX,	V ₁ = 0.4 V	1		-1.6	mΑ
los	Short-circuit output current§	V _{CC} = MAX		_30		85	mА
Icc	Supply current	V _{CC} = MAX		1	60	81	mA

[†]For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions. ‡All typical values are at V_{CC} = 5 V, T_A = 25°C.

 \S{Not} more than one output should be shorted at a time.

switching characteristics, V_{CC} = 5 V, T_A = 25 °C

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
ferrau	Maximum clock frequency		35	50		MHz
tPLH	Propagation delay time, low-to-high-level output from preset	C _L = 15 pF.		15	25	ns
^t PHL	Propagation delay time, high-to-low-level output from clear	$R_L = 400 \Omega$.		18	30	ns
^t PLH	Propagation delay time, low-to-high level output from clock	See Note 2	L	17	30	ns
tPHL	Propagation delay time, high-to-low lèvel output from clock		<u> </u>	20	30	ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.





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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
SN74276DW	OBSOLETE	SOIC	DW	20		TBD	Call TI	Call TI	Samples Not Available
SN74276DWR	OBSOLETE	SOIC	DW	20		TBD	Call TI	Call TI	Samples Not Available
SN74276DWR	OBSOLETE	SOIC	DW	20		TBD	Call TI	Call TI	Samples Not Available
SN74276N	OBSOLETE	PDIP	Ν	20		TBD	Call TI	Call TI	Samples Not Available
SN74276N	OBSOLETE	PDIP	Ν	20		TBD	Call TI	Call TI	Samples Not Available
SN74276N3	OBSOLETE	PDIP	Ν	20		TBD	Call TI	Call TI	Samples Not Available
SN74276N3	OBSOLETE	PDIP	N	20		TBD	Call TI	Call TI	Samples Not Available

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



DW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-013 variation AC.



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